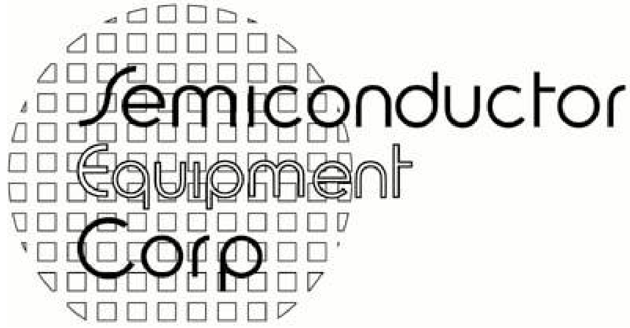

NEWS RELEASE

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S.E.C. New Product Announcement

MOORPARK, California, U.S.A., January 2005 - Semiconductor Equipment Corp. (S.E.C.) continues to enhance its product line by distributing Yamaha's i-CUBE II high-speed, flipchip placement system and automatic die bonder. S.E.C. is the distributor for the US, Canada, and Mexico.

The new i-Cube II will compliment SEC's current line of manual and semi-automatic die bonders, flipchip placement and bonding systems, laser diode bonders, eutectic die bonders, pick-and-place systems, tape applicators, die ejectors, rework stations, wafer dicing tape, UV curable and high purity tapes, and multifunctional bond testers.

The i-CUBE II is a high-speed, automatic die bonder capable of mixed mounting SMD components and semiconductor components as well as handling multiple types of components. It is usable for dipping and stamping by the dipping unit, and it is applicable for dispensing and for a wide area up to L300mm X W200mm. The i-Cube II can be used either as a stand-alone unit or inline.

A combination of precision, high speed, and versatility makes the i-CUBE II the platform of choice for a wide range of applications including accurate chip placement. The i-Cube II has non-contact dispensing and 3-D mounting. The two up-looking cameras coordinate with the down-looking camera to provide the high-performance visual system that allows a sensor to measure the distance from the component to the mounting surface. The load controlled mounting head then picks up the chip and places it exactly—from 1 to 49N.

The multiple accuracy compensation system (MACS) controls the accuracy and precision of the i-CUBE II. This is a unique, real-time compensation system that corrects for zero.

The load controlled mounting provides three types of selectable head units. The FF head affords two pick and place heads with no force control. The FD head offers two pick and place heads

with a vacuum tool and an adhesive dispenser and control force. The 4M head is a four in-line multi-head with full-servo controlled Z axis.

Semiconductor Equipment Corporation is recognized as the leading manufacturer and distributor of standard and customized die handling equipment and semiconductor dicing tape. Since 1975, SEC has installed thousands of production units worldwide for work in packaging and assembly operations including edge-emitting lasers, flip chip, surface mount, and hi-reliability devices such as ball grid arrays, quad flat packs, and multi-chip modules.

(Photo enclosed – Yamaha iCUBE-II)